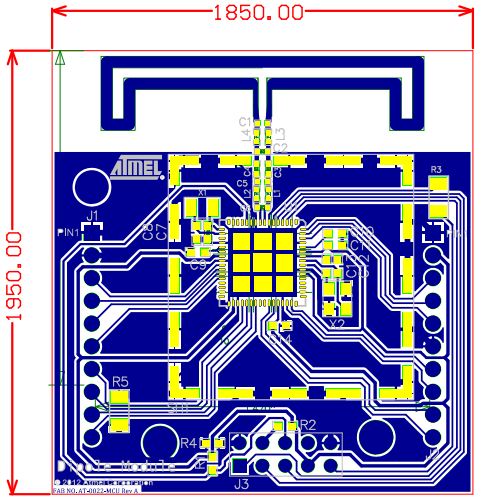
TOP SIDE ASSEMBLY NOTES:

1. THE FOLLOWING COMPONENTS CAN BE POPULATED IN EITHER ORIENTATION:
   ALL RESISTORS AND NON-POLARIZED CAPACITORS CRYSTAL X2
   CONNECTOR J1 RF SHIELD SHD1
2. WATCH FOR POLARITY OR ORIENTATION MARKINGS ON THE FOLLOWING COMPONENTS:
   INDUCTORS L1-L4 INTEGRATED CIRCUIT U1
3. FINISHED ASSEMBLY NEEDS TO BE RoHS COMPLIANT.
4. POPULATE CRYSTAL X1 (BOTTOM SIDE) OR X2 (TOP SIDE) BUT NOT BOTH.

DETAIL A



TOP SILKSCREEN
TOP LAYER

TOP PASTE

TOP SOLDERMASK

NOTES: (UNLESS SPECIFIED UNITS ARE IN INCHES)

1. FABRICATE BOARD PER IPC-A-600C
2. MATERIAL FR-4, LAYERS 2
3. BOARD THICKNESS: 0.062 +/-10%
4. PROVIDE THE PROPER DIELECTRIC FOR ALL LAYERS
5. MINIMUM PLATING ON THROUGH HOLE SHALL BE 0.001 INCH Cu
6. 1/2 OZ. ON TOP & BOTTOM LAYERS
7. FINISH: ELECTROLESS NICKEL IMMERSION GOLD
8. ALL HOLES ARE PLATED THROUGH UNLESS OTHERWISE SPECIFIED
9. HOLE SIZES ARE FINISHED SIZE
10. SOLDER MASK BOTH SIDES WITH BLUE LPI
11. FOR LAYER STACK SEE DETAIL A.
12. SILKSCREEN BOTH SIDES USING WHITE EPOXY OVER SOLDER MASK
13. DEBURR ALL SHARP EDGES.
14. OVERALL BOARD BOW SHOULD NOT EXCEED 0.01

DRILL TABLE

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
○	10	36mil (0.9144mm)	PTH	Round
▽	20	40mil (1.016mm)	PTH	Round
□	3	125mil (3.175mm)	PTH	Round
	33 Total			

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Dipole Module

FAB NO. AT-0022-MCU

REV. A

DATE: Jul 02, 2012 | ENGINEER : | DESIGNER : PAUL ESPIRITU